

HS Thermal Pads

Silicone Thermal Interface Material for HS and 89 series



Thermal silicone provides engineers an ideal material to improve thermal transfer, and lower operating temperatures between components and heat sinks. These thermal pads deliver considerable benefits over traditionally used materials such as thermal greases. The use of thermal pads simplifies the design and engineering process, while reducing inventory and production costs. The HS series of thermal pads was designed specifically for the ARCOL HS series and Ohmite 89 series resistors.



FEATURES

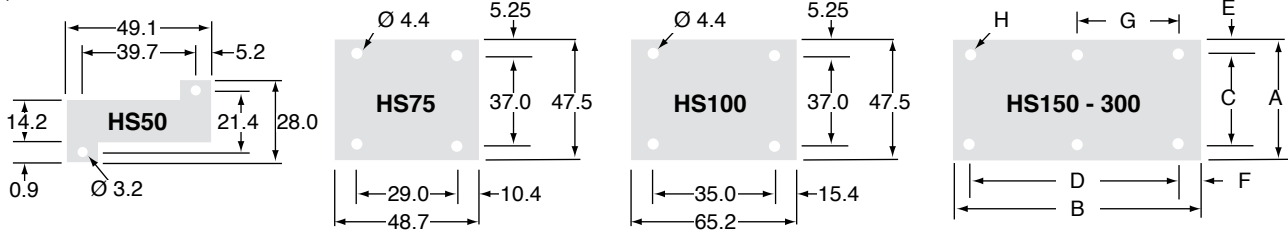
- Excellent Relative Thermal Index (RTI)
- Electrically insulating
- High conformability
- Low durometer
- Naturally tacky
- UL, RoHS, and REACH Compliant
- Compatible with **ARCOL HS** and **Ohmite 89 Series**

CHARACTERISTICS

| | |
|------------------------------|---------------------------|
| Composition | Silicone & Ceramic-filled |
| Color | Light blue |
| Thickness | 0.5mm |
| Hardness | 25 Shore C |
| Cont. Use Temperature | -40 to 150°C |
| Breakdown Voltage | >5 Kv/mm |
| Flame Rating | V-0 |
| Thermal Conductivity | 3.0 W/m.k |

DIMENSIONS

(mm)



| | A | B | C | D | E | F | G | H |
|-------|------|-------|------|-------|------|------|------|-----|
| HS150 | 47.5 | 97.7 | 37.0 | 58.0 | 5.25 | 20.4 | 29.0 | 4.4 |
| HS200 | 72.5 | 89.7 | 57.2 | 70.0 | 7.65 | 10.4 | 35.0 | 5.1 |
| HS250 | 72.5 | 109.7 | 57.2 | 89.0 | 7.65 | 10.4 | 44.5 | 5.1 |
| HS300 | 72.5 | 127.7 | 59.0 | 104.0 | 6.75 | 12.4 | 52.0 | 6.6 |

ORDERING INFORMATION

Standard Part Numbers

HS50-TP2
 Product Type Thermal Pad Material Type

| Pad Part Number | Compatibility | |
|-----------------|---------------|--------------|
| | Ohmite Series | ARCOL Series |
| HS50-TP2 | 850 | HS 50 |
| HS75-TP2 | | HS 75 |
| HS100-TP2 | | HS 100 |
| HS150-TP2 | | HS 150 |
| HS200-TP2 | | HS 200 |
| HS250-TP2 | | HS 250 |
| HS300-TP2 | | HS 300 |